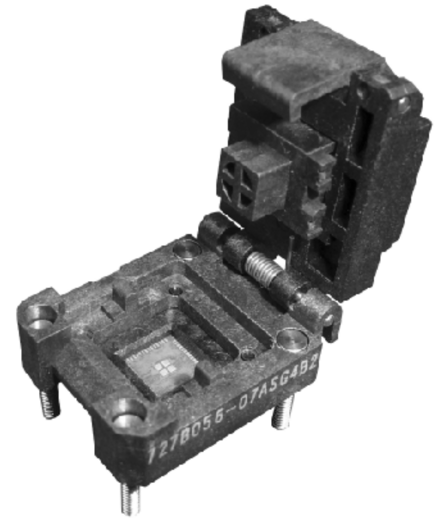
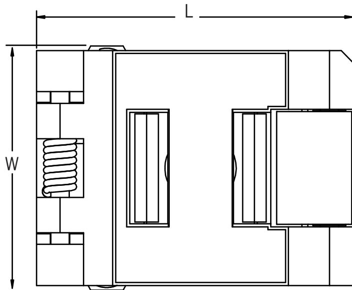
72X SERIES

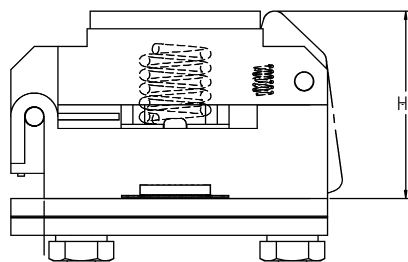
MLF/QFN
BCC/LGA
BGA/μBGA/CSP

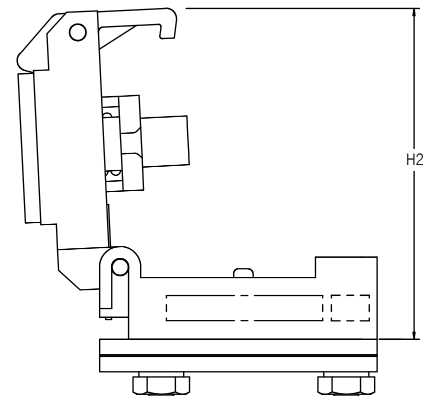
SPECIFICATIONS:

- Handles package sizes 3x3mm to 10x10mm
- Clam shell
- Compression Surface Mount
- Elastomer interface material
- Wedge guided pressure pad for direct Z axis pressure on the package during lid engagement
- HTOL Compatible
- Modular Design: Minimal components
- Adaptable to various package thickness
- Any pitch or pitch combination 0.4mm and greater
- Max I/O = 250





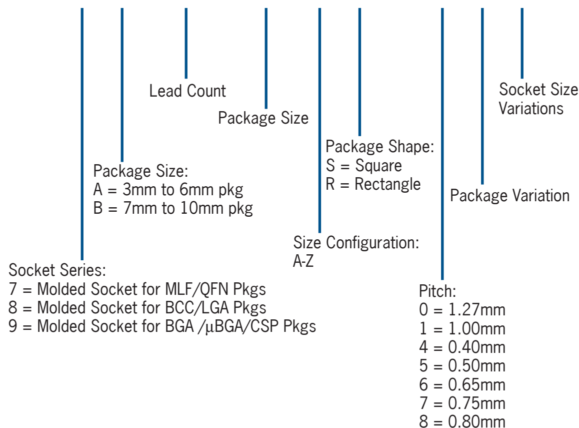




	W	L	H1	H2
72X A	22.0	27.0	16.0	32.1
72X B	22.5	29.0	16.0	34.4

*All dimensions in millimeters

DESCRIPTION & ORDERING INFORMATION



ELASTOMER INTERFACE MATERIAL FEATURES:

- Extremely High Frequency: >20GHz
- Self Inductance: 0.15nH
- Mutual Inductance: 0.04nH
- Mutual Capacitance: 0.013pF
- Contact Resistance: < 50 mΩ
- Current Rating: 0.5 amps per I/O
- Contact Force: 18 grams
- Extremely Coplanar: < 0.001"
- Environmental Capability: - 40°C to 150°C
- Typical Cycle Life: 10,000 insertions
- Multiple Configurable Contact Sites per Pad

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